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Topics

The technical areas include the following, but are not limited to:

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- ·Microelectronic Devices and Integrated Circuits
- ·Computer Science and AI Technology
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- •Electronical Engineering and Automatic Control Important Dates

Paper Submission Deadline: June 10
Notification of Acceptance: June 25
Early-bird Registration: June 30
Final Paper Submission Deadline: June 30, 2023

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